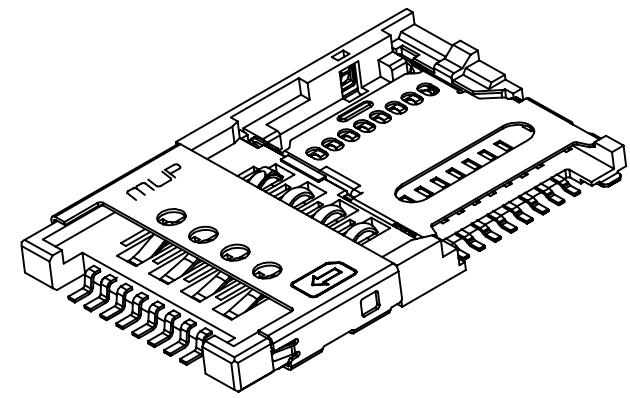
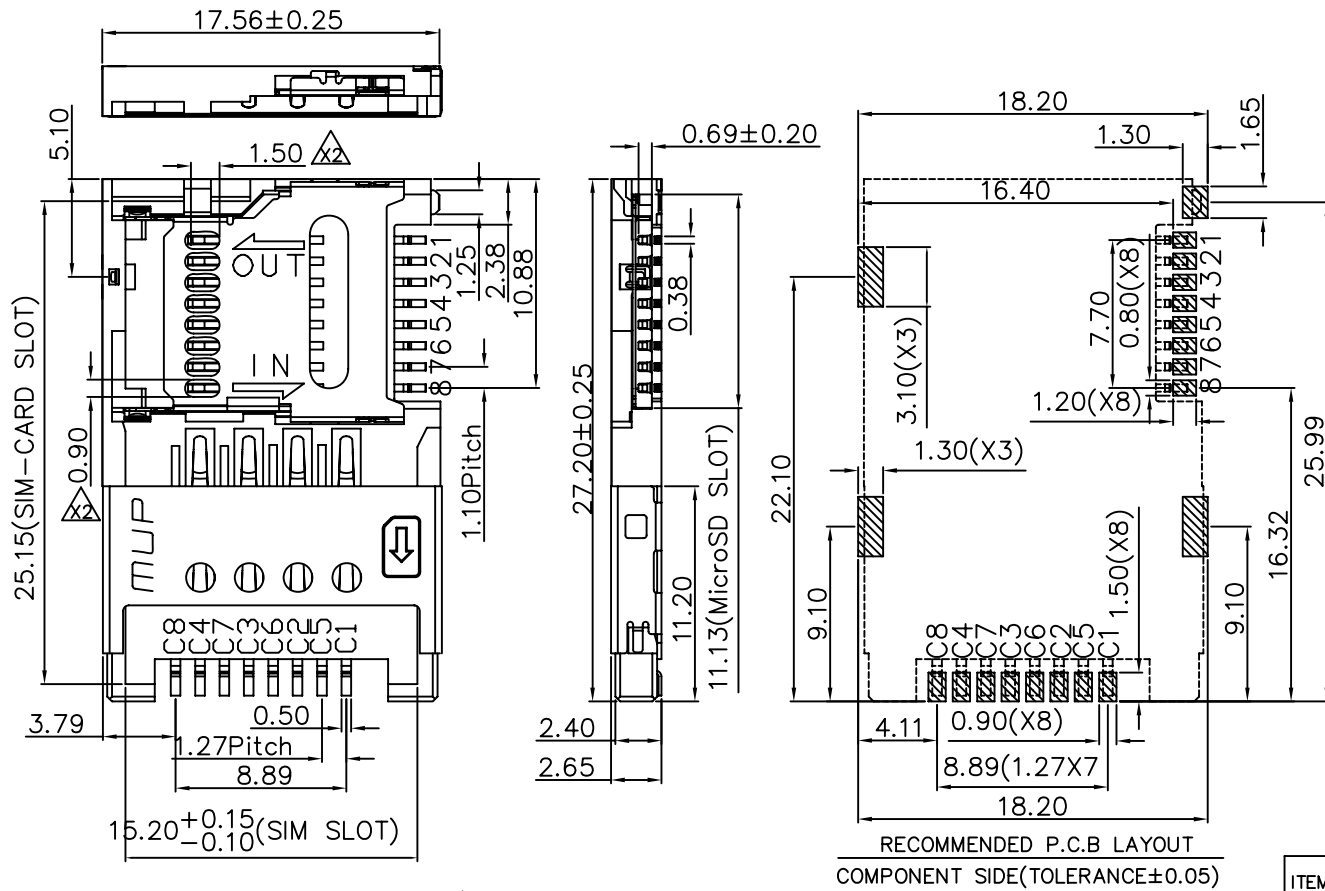
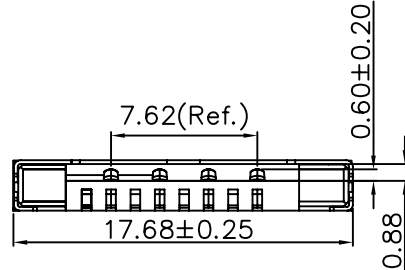


REV.	DESCRIPTION OF REVISIONS	APPR.	DRAW.	RELEASE	DATE
X1					
X2					



Micro SD CARD		SIM CARD	
Pin No.	NAME	Pin No.	NAME
1	DAT2	C1	VCC
2	CD/DAT3	C2	RST
3	CMD	C3	CLK
4	VDD	C4	Reserved
5	CLK	C5	GND
6	VSS	C6	VPP
7	DAT0	C7	I/O
8	DAT1	C8	Reserved

RECOMMENDED P.C.B LAYOUT  
COMPONENT SIDE(TOLERANCE±0.05)



TECHNICAL CHARACTERISTICS

- General Characteristics  
Dimensions: 27.20LX17.68WX2.65H mm  
Weight: Approx 1.22±0.2g  
Durability: 5,000 cycles min.
- Electrical Characteristics  
Contact resistance: 50mΩ typical, 100mΩ max  
Insulation resistance: >1000MΩ/500V DC
- Solderability  
Vapor phase: 215°C, 30sec. Max  
IR reflow: 250°C, 5sec. Max  
Manual soldering: 370°C, 3sec. Max
- Environmental Characteristics  
Operating temperature: -40°C~+85°C  
Operating humidity: 10%~+95%RH

ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	BASE	1	LCP 30%GF	Black UL94V-0
2	SIM TERMINAL	8	C5210R-H	Contact area: 5 μ Au plated Solder tail: 100 μ Sn plated Under plated: 50 μ Ni plated
3	SIM SHELL	1	SUS304R-H	Contact area: 5 μ Au plated Under plated: 50 μ Ni plated
4	Micro SD TERMINAL	8	C5210R-H	Contact area: 5 μ Au plated Solder tail: 100 μ Sn plated Under plated: 50 μ Ni plated
5	HOLDER	1	C2680R-H	Plated: 100 μ Tin over 50 μ Nickel
6	Micro SD SHELL	1	SUS304R-H	

Unless otherwise specified, other tolerance are:

**MUP** MUP INDUSTRIAL CO.,LTD.

NAME: **2 in 1 Card Connector**

MODEL NO: **MUP-M619**

TYPE: **Micro SD8pin+SIM8pin**

PROJ.	UNIT	SCALE	DRAWN	Jimmy Dec.01.2012	DWG NO.:
	MM	1:1	CHECKED	Zoey Dec.01.2012	DWG-MUP-M619-001
CUSTOMER DRAWING			APPROVAL	Simon Dec.01.2012	SHEET
					1/1
					REVISION
					X2

